FPC/FFC Connectors Power up offset (Display)

Applications | Mobile device, Display, PC



- ▶ 0.5mm pitch, 2.25mm height, Horizontal offset type connector
- ▶ Widely used in a variety of markets including PC, TV etc.
- ► Easy mating, 30 cycle durability
- ► High data rate transfer
- Anti-reverse mating design

Code & Specification

Mating Size / Unit : (mm)

Product Code	Pitch (mm)	No. of Contacts	Width (mm)	Height (mm)	Length	Remark
IS100-L30O-C23	1.00	30	4.90	2.25	40.00	-

Rated Current	Contact Resistance	Withstanding voltage	Temperature Range
1.0A/Pin (Applicable Wire : AWG #30)	40mΩ (Max.)	500V AC(RMS)	-35°C ∼ 85°C

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Product Specification

	Rated current	1.0A/Pin	Operating temperature range	-35°C to +85°C	Storage temperature range	15°C to 35°C (With packing)
Ratings	Rated voltage	200V AC(RMS)/DC	Operating humidity range	70%RH Max. 2	Storage humidity range	65%RH Max. 2

¹⁾ Including terminal temperature rise.

²⁾ Storage area is to be free of corrosive gases and dew formation.

Items	Specifications	Conditions
1. Contact resistance	40mΩ [Max.]	Open circuit voltage: 20mV Max.(AC)Test current: 10mA.
2. Insulation resistance	100MΩ [Min.]	100V DC
3. Withstanding voltage	No flashover or dielectric breakdown	500V AC(RMS) for 1minute
4. Insertion Force	6.0kgf [Max.]	Measured force to insert wafer assembly into the housing assembly which has same circuits. (Speed 25mm/Min)
5. Withdrawal Force	0.75kgf [Min]	Measured forces to withdraw wafer assembly from the housing assembly which has same circuits. (Speed 25mm/Min)
6. Durability	Contact resistance - 80mΩ [Max.]	Measured after 30 cycle total insertion and withdrawal operation.
7. Vibration	1) Contact resistance - 80mΩ [Max.] 2) No damage, loose part no crack	 Vibration frequency range: 10~55Hz Total amplitude: 1.5mm Sweep ration: 10-55-10Hz/Min Duration: 2h each (6h in total)
8. Humidity	1) Contact resistance - $80m\Omega$ [Max.] 2) Insulation resistance : $50M\Omega$ [Min.]	Temperature: 40°C±2°CRelative humidity: 90% RH to 95% RHDuration: 96hr
9. Solder heat resistance	No loose contacts no deformation.	Reflow condition. (Refer to Reflow) Temperature 240 to 240 to 150 to -175 to

Materials / Finish

Part	Materials	Finish	UL Regulation
Base	LCP	Black	UL94V-0
Contact Terminal	Phosphor Bronze	Au , Ni plated	-
Guide Terminal	Phosphor Bronze	Sn. Ni plated	-
Cover	Stainless Steel	Pre-plating Sn	-

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Product Drawing 328 Recommended PCB, Metal Mask Layout D±0.1 1.2±0.1 1±0.05(pitch) 0.6±0.05 0.8±0. 2.2 ± 0.05 1.5±0.1 0.5±0.05 (1) NO.1 NO.32 1±0.1 (0.3)E±0.05 RECOMMENDED PAD LAYOUT (Metal Mask 개구부 Size 1:1 t0.10)

Mating Size / Unit : (mm)

Product No.	No. of Contacts	А	В	С	D	E
IS100-L30O-C23	30	31.00	29.00	40.00	40.65	37.65